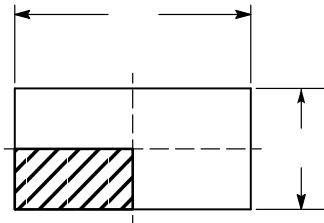


**ULLGA8, 1.95x1.0, 0.5P**  
CASE 613AC-01  
ISSUE A

DATE 13 FEB 2008

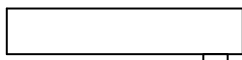
SCALE 8:1



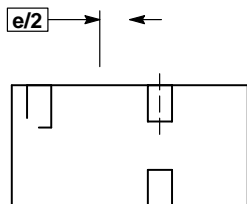
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
4. A MAXIMUM OF 0.05 PULL BACK OF THE PLATED TERMINAL FROM THE EDGE OF THE PACKAGE IS ALLOWED.

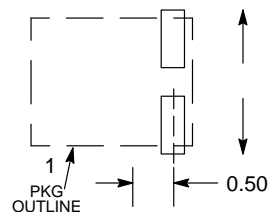
For details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



**MOUNTING FOOTPRINT**



NOTE 4



|                         |                               |  |
|-------------------------|-------------------------------|--|
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| <b>DESCRIPTION:</b>     | <b>ULLGA8, 1.95X1.0, 0.5P</b> | <b>PAGE 1 OF 1</b>   |

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